Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"20030214049"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/08 09:46
L2	1605	die and substrates and circuit adj board.clm.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/08 11:01
L3	5820	(257/724,725,726,727,678).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/12/08 11:01
S1	132	MEMS ADJ PACKAGE	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/07 14:44
S2	1065	MEMS and seal$3 and gold and tin	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/07 14:45
S3	2013	MEMS and seal$3 and copper and tin	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/07 15:12
S4	1336	MEMS and seal$3 and copper and tin and thickness	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/07 17:17
S5	1630	packag$3 and corners and stress and resin and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/07 17:19
S6	1	("6242801").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/08 09:36